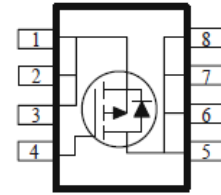
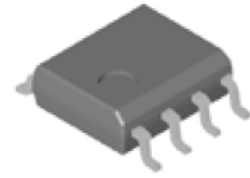


LP4565T1G

P-Channel 60-V (D-S) MOSFET

SO-8



1. Key Features:

- Low $r_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed

2. Typical Applications:

- Load Switches
- DC/DC Conversion
- Motor Drives

3. ORDERING INFORMATION

| Device | Marking | Shipping |
|-----------|---------|----------------|
| LP4565T1G | LP4565 | 4000/Tape&Reel |

4. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$ unless otherwise stated)

| Parameter | Symbol | Limits | Unit | |
|--|-----------|--------------------------|------------------|---|
| Drain-to-Source Voltage | VDSS | -60 | V | |
| Gate-to-Source Voltage | VGS | ± 20 | V | |
| Continuous Drain Current(Note 1) | ID | $T_A = 25^\circ\text{C}$ | -7 | A |
| | | $T_A = 70^\circ\text{C}$ | -5 | |
| Pulsed Drain Current (Note 2) | IDM | -20 | A | |
| Continuous Source Current (Diode Conduction)(Note 1) | IS | -1.6 | A | |
| Power Dissipation(Note 1) | PD | $T_A = 25^\circ\text{C}$ | 2.9 | W |
| | | $T_A = 70^\circ\text{C}$ | 1.8 | |
| Operating Junction and Storage Temperature Range | TJ , TSTG | -55 ~+150 | $^\circ\text{C}$ | |

Note: 1.Surface Mounted on 1" x 1" FR4 Board.

2.Pulse width limited by maximum junction temperature.

5. THERMAL CHARACTERISTICS

| Parameter | Symbol | Max | Unit | |
|--------------------------------------|---------------|---------------------|------|--------------------|
| Maximum Junction-to-Ambient (Note 1) | R θ JA | $t \leq 10\text{S}$ | 45 | $^\circ\text{C/W}$ |
| | | Steady State | 95 | |

6. Electrical Characteristics

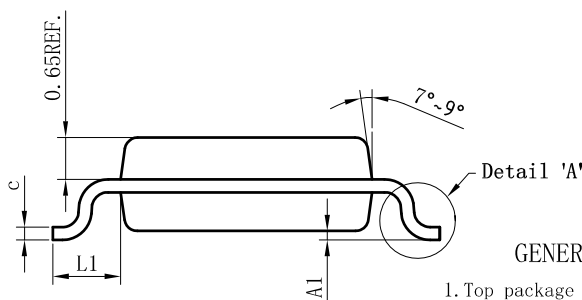
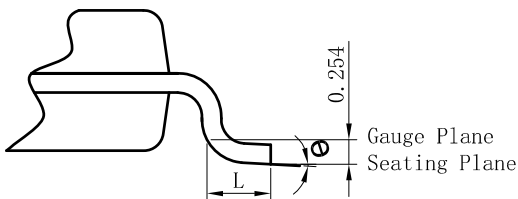
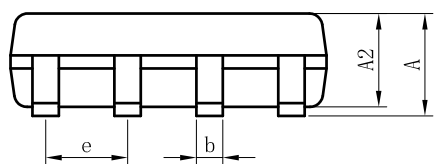
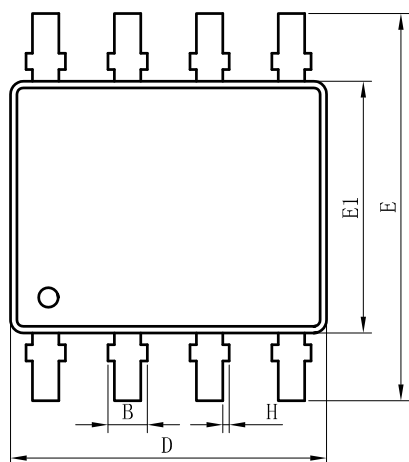
| Characteristic | Symbol | Min. | Typ. | Max. | Unit |
|---|--------------|---|-------|----------|------------|
| Static | | | | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250 \mu A$ | -1 | | V |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | ± 10 | μA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -48 V, V_{GS} = 0 V$ | | -1 | μA |
| | | $V_{DS} = -48 V, V_{GS} = 0 V, T_J = 55^\circ C$ | | -10 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} = -5 V, V_{GS} = -10 V$ | -7.5 | | A |
| Drain-Source On-Resistance ^a | $r_{DS(on)}$ | $V_{GS} = -10 V, I_D = -4 A$ | | 82 | m Ω |
| | | $V_{GS} = -4.5 V, I_D = -3.2 A$ | | 100 | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = -15 V, I_D = -4 A$ | 9 | | S |
| Diode Forward Voltage ^a | V_{SD} | $I_S = -2.1 A, V_{GS} = 0 V$ | -0.83 | | V |
| Dynamic ^b | | | | | |
| Total Gate Charge | Q_g | $V_{DS} = -30 V, V_{GS} = -4.5 V,$ $I_D = -4 A$ | | 10 | nC |
| Gate-Source Charge | Q_{gs} | | | 4.2 | |
| Gate-Drain Charge | Q_{gd} | | | 3.1 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DS} = -30 V, R_L = 7.5 \Omega,$ $I_D = -4 A,$ $V_{GEN} = -10 V, R_{GEN} = 6 \Omega$ | | 7 | ns |
| Rise Time | t_r | | | 5 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 37 | |
| Fall Time | t_f | | | 14 | |
| Input Capacitance | C_{iss} | $V_{DS} = -15 V, V_{GS} = 0 V, f = 1 Mhz$ | | 1146 | pF |
| Output Capacitance | C_{oss} | | | 84 | |
| Reverse Transfer Capacitance | C_{rss} | | | 60 | |

Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

OUTLINE AND DIMENSIONS

SOP8

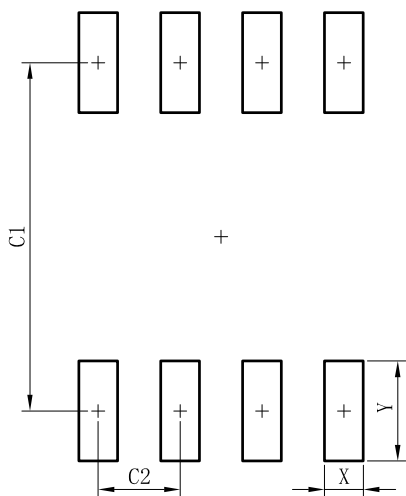


| SOP8 | | | |
|----------------------|---------|------|------|
| DIM | MIN | NOR | MAX |
| A | - | - | 1.75 |
| A1 | 0.10 | 0.15 | 0.20 |
| A2 | 1.35 | 1.45 | 1.55 |
| b | 0.33 | 0.42 | 0.51 |
| c | 0.15 | 0.22 | 0.29 |
| D | 4.77 | 4.90 | 5.03 |
| E | 5.80 | 6.00 | 6.20 |
| E1 | 3.80 | 3.90 | 4.00 |
| e | 1.27BSC | | |
| L | 0.46 | 0.66 | 0.86 |
| L1 | 0.85 | 1.05 | 1.25 |
| θ | 0° | 5° | 8° |
| B | - | - | 0.55 |
| H | 0 | 0.05 | 0.10 |
| All Dimensions in mm | | | |

GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um
4. Package Body Sizes Exclude Mold Flash, Protrusion Or Gate Burrs. Mold Flash, Protrusion Or Gate Burrs Shall Not Exceed 0.10 mm Per Side.
5. Dimension "b" Does Not Include Dambar Protrusion.

SOLDERING FOOTPRINT



| SOP8 | |
|------|------|
| DIM | (mm) |
| X | 0.60 |
| Y | 1.55 |
| C1 | 5.40 |
| C2 | 1.27 |

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